



AD7746 Level Demo PCB Rev. C – Component Side View.

Layer 1 – Component Side

Drill Drawing

- Material: Four layer, FR4 glass epoxy laminate, 0.062' +/- .007' thick.
1 oz. copper clad – external layers. 1 oz. copper clad – internal layers.
Material to be RoHS compliant.
- Plated thru holes and the conductive pattern electroplated with 0.001' min. thick copper. Terminal areas and plated thru holes to be ENIG plated.
Soldermask over bare copper.
- Finished Board to be RoHS Compliant
- Datum for (x,y) co-ordinate drill files at LLH corner.
- Processing tolerances:
 - Conductive pattern front to back registration within .005' total.
 - Minimum annular ring surrounding holes: 0.002'
 - Finished conductive pattern within .002' of true size.
- Warp and twist within .010 inch per inch
- Dimensions are for the finished part.
- Solder Mask: Liquid photo imangible solder mask over bare copper (smobc), colour green, both sides using the patterns provided. No mask is permitted on the terminal areas. Soldermask to etch registration within .005' total.
- Screening: Screen component outlines and nomenclature using indelible white ink on the primary and secondary sides (as required). Nomenclature shall be legible. Screen to etch registration within .020' total.
- Surfaces: Punched or machined surfaces 125 micro inches rms max.
- Break all sharp edges .015' R max.
- Manufacturer to add Manufacturers ID, UL Vendor & Date Code (YY/WW format) in the area within this box on the component side silkscreen layer

SIZE	QTY	SYM	PLATED	TOL
37	10	+	YES	+/-2.0
41	5	x	YES	+/-2.0
25	4	□	YES	+/-2.0